

EP2614 LOW VISCOSITY EPOXY ADHESIVE

• PRODUCT DESCRIPTION

EP2614 is a low viscosity, fast curing, electrically insulating epoxy adhesive. Capillary flow low viscosity underfill which withstands several cycles of 260°C. EP2614 is available as 1 or 2 component. Suitable for metal, plastics, ceramics and ferrite bonding applications.

• CURING PROPERTIES

100°C	125°C	150°C	180°C
50-60 min	30 min	5 min	< 1 min
Pot Life @ 25° C: 3 days			

• PHYSICAL PROPERTIES

Color	Amber
Viscosity (mixed)	400 Cps
Specific Gravity	1,13
Mix ratio (by weight)	100:8

• INSTRUCTIONS FOR USE

Temperature Resistance (°C)	-40 to 260
Hardness Shore D	80
Lap Shear Strength (Psi)	2250
Chlorine Content (µg/g)	6
Sodium Content (µg/g)	3
Potassium Content (µg/g)	< 1
Tg (°C)	125
Volume Resistivity	
• 100 V (Ω-cm)	6.2 x 10 ¹⁵
• 500 V (Ω-cm)	4.6 x 10 ¹⁵
Dielectric Constant	
• 120 Hz	3.5
• 1000 Hz	3.4
Dissipation Factor	
• 120 Hz	0.007
• 1000 Hz	0.008
Dielectric Strength	V/mil: 436 V/mm: 17



EP2614 LOW VISCOSITY EPOXY ADHESIVE

• INSTRUCTIONS FOR USE

The surfaces should be free of dust, oil and other dirt in order to obtain an optimal efficient bond.

Shelf life: Store in original, unopened containers for 12 months at room temperature

The resin of part B might cristalize during storage. This process is reversible by heating (1 hour @ 60°C).

